

Supporting Information

One-step process for superhydrophobic metallic surfaces by wire electrical discharge machining

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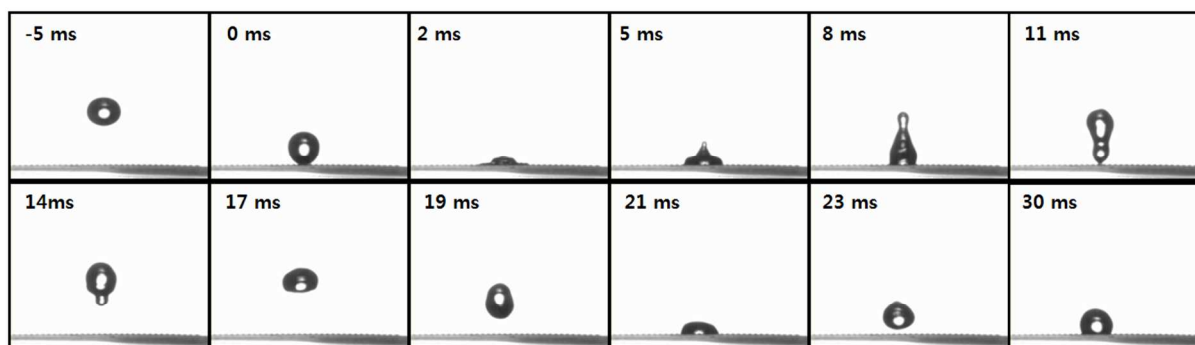
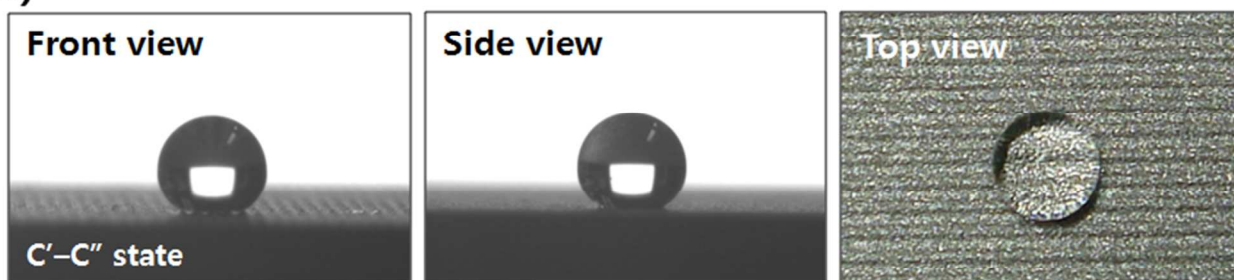


Figure S1. Snapshots of high-speed camera images of a bouncing water droplet on the fabricated superhydrophobic metal substrate in **Figure 1C** ($\lambda = 500 \mu\text{m}$, 1st cutting).

(a)



(b)

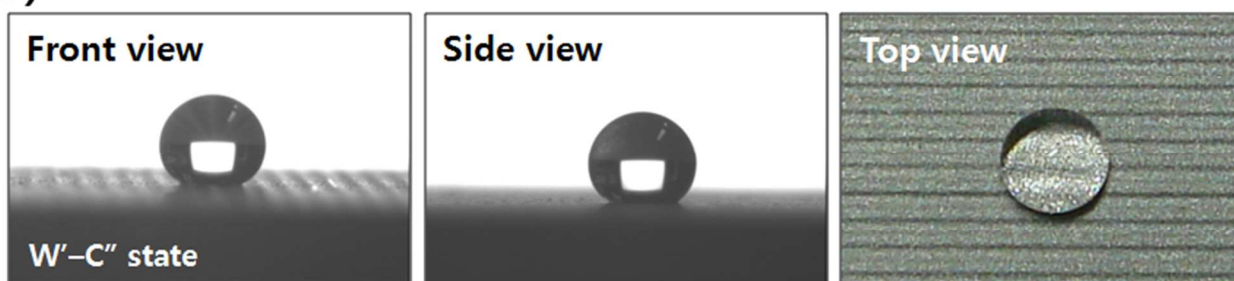


Figure S2. Optical images of water droplets on fabricated metallic surfaces with (a) $C'-C''$ and (b) $W'-C''$ states. In the $C'-C'$ state, the CAs are nearly the same when viewed from the front and the side. On the other hand, in the $W'-C''$ state, the CAs show a slight difference (less than 5°) in the two directions.

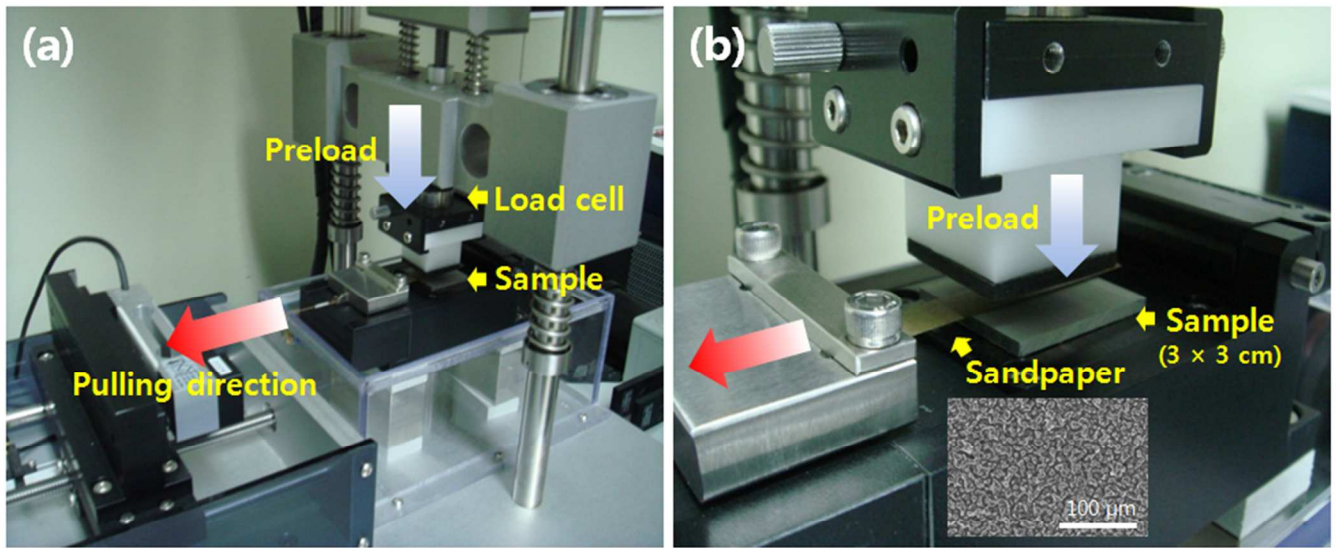


Figure S3. Optical images of the custom-built equipment for the scratching experiment: (a) A P3000 sandpaper (mean particle diameter: 7 μm , 1 cm in width) was placed on the fabricated dual-roughness surface and pressed under a controlled preload ($\sim 3 \text{ N/cm}^2$). Then the sandpaper was pulled to induce a scratch. (b) This magnified image show the location and surface profile of the P3000 sandpaper.

Table S1. WEDM process conditions used in the experiment.

WEDM Step	Positive voltage[v]	Negative voltage[v]	Current[A]	Positive duration	Negative duration	Roughness [Ra]	Roughness factor
1 st Cut	+126 V	-80 V	150 A	28 μ s	50 μ s	4.16 μ m	1.44
2 nd Cut	+106 V	-80 V	42 A	30 μ s	50 μ s	2.37 μ m	1.33
3 rd Cut	+106 V	-76 V	12 A	14 μ s	20 μ s	0.94 μ m	1.23
4 th Cut	+84 V	-74 V	6 A	15 μ s	20 μ s	0.41 μ m	1.13